

Substitute for Form 1449 (Rev. 10/97)

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

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Continuation of Form 1449

Application Number	09/961034
Filing Date	September 21, 2001
First Named Inventor	Datta, Madhav
Group Art Unit	2814
Examiner Name	Pham, Long

Attorney Docket No: 884.522US1

Sheet 1 of 1

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	Y ¹
LP		"Chromium Copper Step Phasing", IBM Technical Disclosure Bulletin, (08/01/1977), pgs. 1005-1008	
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DATE CONSIDERED

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